# MICROELECTRONIC COMPONENT ASSEMBLIES EMPLOYING LEAD FRAMES HAVING REDUCED-THICKNESS INNER LENGTHS

## ABSTRACT OF THE DISCLOSURE

The present disclosure suggests various microelectronic component assembly designs and methods for manufacturing microelectronic component assemblies. In one particular implementation, a microelectronic component assembly includes a microelectronic component, at least two leads, and at least two bond wires. Each of the leads may have a reduced-thickness inner length adjacent terminals of the microelectronic component and a body having an outer surface spaced farther from the microelectronic component than a bond surface of the inner length. Each of the bond wires couples the microelectronic component to one of the leads and has a maximum height outwardly from the microelectronic component that is no greater than the height of the outer surface of the lead.

**FIGURE 2**



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